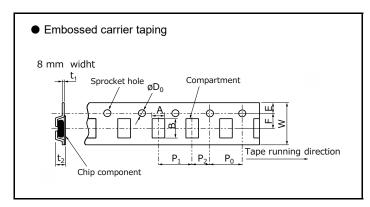
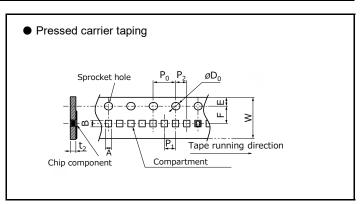
# 2 Mode Noise Filters / Packaging methods

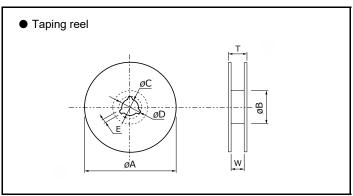
# Packaging methods (Taping)

### Standard quantity

Part number	Size (inch)	Kind of taping	Pitch (P <sub>1</sub> ) (mm)	Quantity (pcs / reel)
EXC14CP□□□U	0302	Embassed corrier tening	2	10,000
EXC24CP/CB = = U	0504	Embossed carrier taping	4	5,000
EXC24CN	0504	Pressed carrier taping	2	10,000







### Embossed carrier dimensions

Unit : mm

Part number	Α	В	W	F	Е	P <sub>1</sub>	P <sub>2</sub>	P <sub>0</sub>	$\phi D_0$	t <sub>1</sub>	t <sub>2</sub>
EXC14CP	0.75±0.10	0.95±0.10	8.0±0.2	3.50±0.05	1.75±0.10	2.0±0.1	2.0±0.1	4.0±0.1	1.5 +0.1	0.25±0.05	0.85±0.15
EXC24CP	1 20+0 15	1.45±0.15	8.0±0.2	2 50+0 10	1.75±0.10	4.0±0.1	2.0±0.1	4.0±0.1	1.5 +0.1	0.25±0.05	0.00±0.15
EXC24CB	1.20±0.15   1.45±0.15	0.0±0.2 3.50±0.10	1.75±0.10	4.0±0.1	+.UIU.1 2.UIU.1	2.010.1 4.010.1	1.5 0	0.25±0.05	0.90±0.15		

### Pressed carrier dimensions

Unit : mm

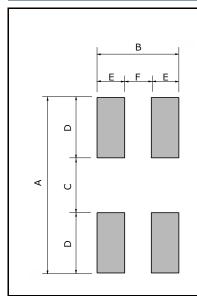
Part number	Α	В	W	F	Е	P <sub>1</sub>	$P_2$	P <sub>0</sub>	øD <sub>0</sub>	t <sub>2</sub>
EXC24CN	1.14±0.10	1.38±0.15	8.0±0.2	3.5±0.1	1.75±0.10	2.0±0.1	2.0±0.1	4.0±0.1	1.5 +0.1	0.68±0.10

#### Standard reel dimensions

Unit : mm

Part number	øΑ	øΒ	øС	øD	E	W	Т
EXC14C	180.0±3.0	60.0±1.0	13.0±0.5	21.0±0.8	2.0±0.5	9.0±0.3	11.4±1.5
EXC24C	160.0±3.0	00.0±1.0	13.0±0.5	21.0±0.6	2.0±0.5	9.0±0.3	11.4±1.5

# Recommended land pattern design



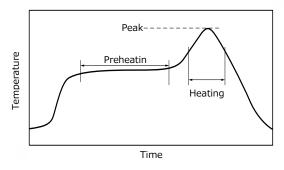
Unit : mm								
Part number	Dimensions							
Part number	Α	В	С	D	Е	F		
EXC14CP	0.80 to 1.00	0.80	0.30	0.25 to 0.35	0.30	0.20		
EXC24CP	1.50 to			0.50 to				
EXC24CB	1.90	1.10	0.50	0.30 to	0.40	0.30		
EXC24CN	1.90			0.70				

# **Recommended soldering conditions**

Recommendations and precautions are described below

#### Recommended soldering conditions for reflow

- Reflow soldering shall be performed a maximum of two times.
- Please contact us for additional information when used in conditions other than those specified.
- Please measure the temperature of the terminals and study every kind of solder and printed circuit board for solderability before actual use.



### For soldering (Example: Sn-37Pb)

	Temperature	Time
Preheating	140 ℃ to 160 ℃	60 s to 120 s
Main heating	Above 200 ℃	30 s to 40 s
Peak	235 ± 10 °C	max. 10 s

## For lead-free soldering (Example :Sn-3Ag-0.5Cu)

	Temperature	Time						
Preheating	150 ℃ to 170 ℃	60 s to 120 s						
Main heating	Above 230 ℃	30 s to 40 s						
Peak	max. 260 ℃	max. 10 s						

#### Flow soldering

·We do not recommend flow soldering, because flow soldering may cause bridges between the electrodes.

《Repair with hand soldering》

- Preheat with a blast of hot air or similar method. Use a soldering iron with a tip temperature of 350 °C or less.
  Solder each electrode for 3 seconds or less.
- Never touch this product with the tip of a soldering iron.